

## Product Change Notice (PCN)

**Subject:** Transfer of the Solder Plating Site from Carsem S-Site to Carsem M-Site for the Listed Renesas Products

**Publication Date:** 8/8/2019

**Effective Date:** 11/8/2019

**Revision Description:**

Initial Release

**Description of Change:**

Carsem is discontinuing the SnPb plating process at their S-Site and transferring the product to their M-Site location in Ipoh Malaysia.

**Products Impacted:**

<u>Renesas Part Number</u>	<u>Vendor Item Drawing Number</u>
ISL3282EMRTEP-TK	V62/10601-01XB
ISL3298EMRTEP-TK	V62/10602-01XB

**Reason for Change:**

Carsem S-site discontinuing SnPb Plating process due to underutilization. Products plated at Carsem S-Site are being moved to Carsem M-Site to better utilize existing capacity and capability.

**Impact on fit, form, function, quality & reliability:**

The change will have no impact on the form, fit, function, quality, reliability and environmental compliance of the devices.

**Product Identification:**

Product affected by this change is identifiable via the Renesas internal traceability system.

**Qualification status:** Complete, see attached

**Sample availability:** 8/8/2019

**Device material declaration:** Available upon request

*Questions or requests pertaining to this change notice, including additional data or samples, must be sent to Intersil within 30 days of the publication date.*

For additional information regarding this notice, please contact your regional change coordinator (below)			
Americas: <a href="mailto:PCN-US@INTERSIL.COM">PCN-US@INTERSIL.COM</a>	Europe: <a href="mailto:PCN-EU@INTERSIL.COM">PCN-EU@INTERSIL.COM</a>	Japan: <a href="mailto:PCN-JP@INTERSIL.COM">PCN-JP@INTERSIL.COM</a>	Asia Pac: <a href="mailto:PCN-APAC@INTERSIL.COM">PCN-APAC@INTERSIL.COM</a>

Appendix A - Qualification Results (see attached)

**Appendix A:**

3 Qualification lots from Carsem (M-Site) at 3 different dates for Solder Plating.

Lot details as below:

LD	PKG	DEVICE	CSM M PLATE DATE	LOT_QTY
8	MLPD2X3W	ISL3282EMRTEP-TK	2019 Apr 15	1999
8	MLPD2X3W	ISL3282EMRTEP-TK	2019 Apr 23	1985
8	MLPD2X3W	ISL3282EMRTEP-TK	2019 Apr 18	2000

**Plating thickness / composition:**

Plating thickness spec: 300- 1000 micro inch

Plating composition spec: 70 – 90 % Sn (balance Pb)

Measuring equipment: XRF machine

Plating Parameter used: 120 +/- 10 Amp (similar to S site setting, same machine model at M site)

S/size: 6 unit/lot

SUBLOT SERIAL NUMBER	PLATING THICKNESS READING (MICRO INCH)						MIN	MAX	MEAN
	1	2	3	4	5	6			
S201851105512-01	497	535	521	556	501	499	497	556	518
S201851105513-01	511	565	489	543	529	533	489	565	528
S201851105514-01	516	542	555	562	526	543	516	562	540

SUBLOT SERIAL NUMBER	PLATING COMPOSITION (% Sn)						MIN	MAX	MEAN
	1	2	3	4	5	6			
S201851105512-01	84	84	85	84	86	84	84	86	85
S201851105513-01	85	85	84	84	85	84	84	85	84
S201851105514-01	84	85	86	86	85	85	84	86	85

**Plating visual inspections:**

Plating inspection method: Scope 30X magnification

S/size: 100 % inspections for each lot upon received at S site (after complete plating at M site)

SUBLOT SERIAL NUMBER	QTY UNITS	QTY FRAME	PLATING DEFECTS UNITS	DEFECT PPM
S201851105512-01	1985	2 FRAME	0	0
S201851105513-01	2000	2 FRAME	0	0
S201851105514-01	1999	2 FRAME	0	0

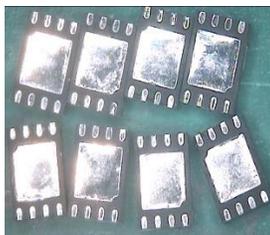
**Solderability Test:**

Solder pot type: Sn /Pb

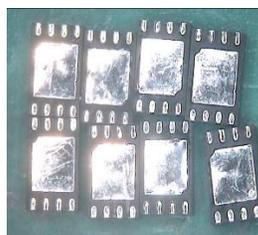
Solder pot temp: 245 +/- 5 DegC

Precondition: Normal test (no precondition)

S/size: 22 unit /lot.



S201851105512-01



S201851105513-01

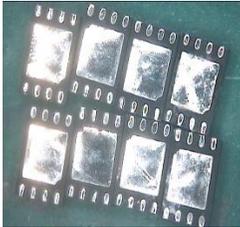


S201851105514-01

All the 22 units/lot passed normal solderability test with good wetting.

**Solderability Test (16-hour dry bake @ 150DegC):**

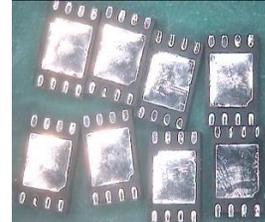
Solder pot type: Sn /Pb  
 Solder pot temp: 245 +/- 5 DegC  
 Precondition: 16-hour Dry Bake @ 150 Deg C  
 S/size: 22 unit /lot.



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S201851105513-01



S201851105514-01

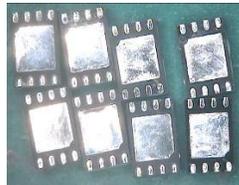
All the 22 units/lot passed 16hrs dry bake solderability test with good wetting.

**Solderability Test (16-hour Steam Age):**

Solder pot type: Sn /Pb  
 Solder pot temp: 245 +/- 5 DegC  
 Precondition: 16-hour Steam Age  
 S/size: 22 unit /lot.



S201851105512-01



S201851105513-01



S201851105514-01

All the 22 units/lot passed 16hr steamage solderability test with good wetting.